

ABSTRACT

A dicing die-bonding integrated film includes a base material layer; an adhesive layer having a first surface facing the base material layer and a second surface on the opposite side of the first surface; and a bonding adhesive layer provided so as to cover a central part of the second surface. The adhesive layer has a first region including a predetermined region in the bonding adhesive layer; and a second region located so as to surround the first region, and an adhesive force of the first region is lower than that of the second region. In the adhesive layer, the difference between the adhesive force of the first region of the adhesive layer toward the bonding adhesive layer and the adhesive force of the second region of the adhesive layer toward the bonding adhesive layer, as measured under predetermined conditions, is 6.5 to 9.0 N/25 mm.

Fig. 5